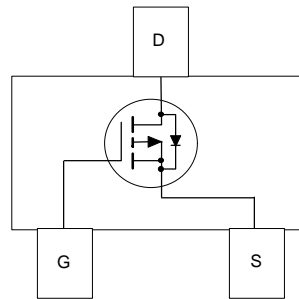
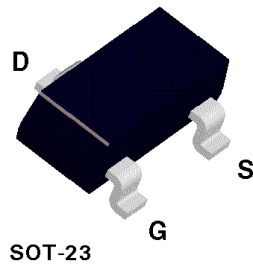


**General Description**

These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process has been designed to minimize on-state resistance, provide rugged and reliable performance and fast switching. They can be used, with a minimum of effort, in most applications requiring up to 0.18A DC and can deliver pulsed currents up to 1A. This product is particularly suited to low voltage applications requiring a low current high side switch.

**Features**

- -0.18A, -60V.  $R_{DS(ON)} = 5\Omega$  @  $V_{GS} = -10V$ .
- Voltage controlled p-channel small signal switch.
- High density cell design for low  $R_{DS(ON)}$ .
- High saturation current.



**Absolute Maximum Ratings**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	NDS0605	Units
$V_{DSS}$	Drain-Source Voltage	-60	V
$V_{DGR}$	Drain-Gate Voltage ( $R_{GS} \leq 1\text{ M}\Omega$ )	-60	V
$V_{GSS}$	Gate-Source Voltage - Continuous	$\pm 20$	V
$I_D$	Drain Current - Continuous	-0.18	A
	- Pulsed	-1	
$P_D$	Maximum Power Dissipation $T_A = 25^\circ\text{C}$	0.36	W
	Derate above $25^\circ\text{C}$	2.9	mW/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/16" from case for 10 seconds	300	$^\circ\text{C}$

**THERMAL CHARACTERISTICS**

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	350	$^\circ\text{C/W}$
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NDS0605

ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25°C unless otherwise noted)							
Symbol	Parameter	Conditions	Min	Typ	Max	Units	
<b>OFF CHARACTERISTICS</b>							
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = -10 μA	-60			V	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -48 V, V <sub>GS</sub> = 0 V			-1	μA	
			T <sub>J</sub> = 125°C			-500	μA
I <sub>GSSF</sub>	Gate - Body Leakage, Forward	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V			100	nA	
I <sub>GSSR</sub>	Gate - Body Leakage, Reverse	V <sub>GS</sub> = -20 V, V <sub>DS</sub> = 0 V			-100	nA	
<b>ON CHARACTERISTICS (Note 1)</b>							
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250 μA	-1		-3	V	
			T <sub>J</sub> = 125°C	-0.6		-2.8	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -0.5 A			5	Ω	
			T <sub>J</sub> = 125°C			10	
			V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -0.25 A			7.5	
			T <sub>J</sub> = 125°C		15		
I <sub>D(on)</sub>	On-State Drain Current	V <sub>GS</sub> = -10 V, V <sub>DS</sub> = -10 V	-0.6			A	
			V <sub>GS</sub> = -4.5 V, V <sub>DS</sub> = -10 V	-0.25			
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -0.2 A	0.07			S	
<b>DYNAMIC CHARACTERISTICS</b>							
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz			60	pF	
C <sub>oss</sub>	Output Capacitance				25	pF	
C <sub>riss</sub>	Reverse Transfer Capacitance				5	pF	
<b>SWITCHING CHARACTERISTICS (Note 1)</b>							
t <sub>D(on)</sub>	Turn - On Delay Time	V <sub>DD</sub> = -30 V, I <sub>D</sub> = -0.2 A, V <sub>GS</sub> = -10 V, R <sub>GEN</sub> = 25 Ω			10	nS	
t <sub>r</sub>	Turn - On Rise Time				15	nS	
t <sub>D(off)</sub>	Turn - Off Delay Time				15	nS	
t <sub>f</sub>	Turn - Off Fall Time				20	nS	
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>							
I <sub>S</sub>	Continuous Source Diode Current				-0.18	A	
I <sub>SM</sub>	Maximum Pulsed Source Diode Current (Note 1)				-1	A	
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -0.5 A (Note 1)			-1.5	V	
			T <sub>J</sub> = 125°C			-1.3	

Note :  
1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.